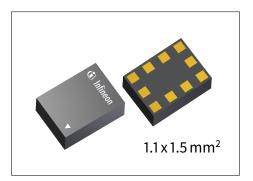




Low Noise Amplifier with Gain Control

Features

- Operating frequencies: 5.15 5.925 GHz
- Insertion power gain: 20.5 dB
- Gain dynamic range: 27 dB
- Low noise figure: 1.6 dB
- Low current consumption: 5.0 mA
- Multi-state control: Gain- and Bypass-Modes
- Small ATSLP leadless package



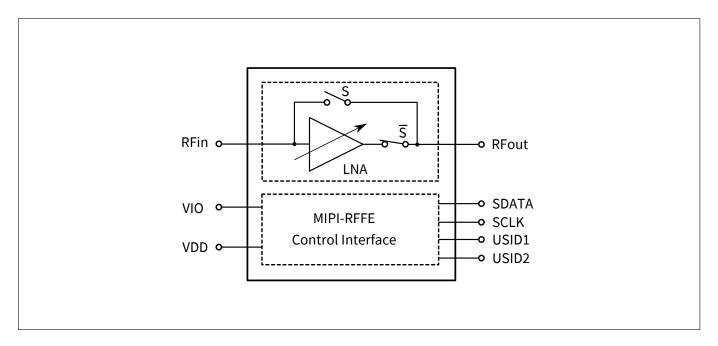
Application

The LTE data rate can be significantly improved by using the high gain LNA. The integrated gain control and bypass function increases the overall system dynamic range and leads to more flexibility in the front-end. In high gain mode the BGAU1A10 offers best Noise Figure to ensure high data rates even on the LTE cell edge. Closer to the basestation the bypass mode can be activated reducing current consumption. Thanks to the MIPI control interface, control lines are reduced to a minimum.

Product Validation

Qualified for industrial applications according to the relevant tests of JEDEC47/20/22.

Block diagram



Low Noise Amplifier with Gain Control

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Table of Contents

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Maximum Ratings

1 Maximum Ratings

Table 1: Maximum Ratings

Parameter	Symbol		Values		Unit	Note / Test Condition
		Min.	Min. Typ.			
Supply Voltage VDD	V _{DD}	-0.3	_	2.5	V	1
Voltage at RFin	V _{RFI}	-1	-	1	V	-
Voltage at RFout	V _{RFO}	-1	-	1	V	-
Current into pin VDD	I _{DD}	-30	-	-	mA	-
RF input power	P _{IN}	-	-	25	dBm	-
Total power dissipation	P _{tot}	-	-	90	mW	
Junction temperature	TJ	-	-	150	°C	-
Ambient temperature range	T _A	-30	-	85	°C	-
Storage temperature range	T _{STG}	-55	-	150	°C	-
ESD capability, HBM	V _{ESD_HBM}	-1000	-	1000	V	2
RFFE Supply Voltage	V _{IO}	-0.5	-	2.7	V	-
RFFE Supply Voltage Levels	V _{SCLK} ,	-0.7	-	V _{IO} +0.7	V	-
KEEL Supply vollage Levels	V _{SDATA}			(max. 2.7)		

¹All voltages refer to GND-Nodes unless otherwise noted

²Human Body Model ANSI/ESDA/JEDEC JS-001-2014 ($R = 1.5 \text{ k}\Omega$, C = 100 pF).

Attention: Stresses above the max. values listed here may cause permanent damage to the device. Maximum ratings are absolute ratings; exceeding only one of these values may cause irreversible damage to the integrated circuit. Exposure to conditions at or below absolute maximum rating but above the specified maximum operation conditions may affect device reliability and life time. Functionality of the device might not be given under these conditions.



RF Characteristics

2 DC Characteristics

Table 3: DC Characteristics at $T_A = 25 \,^{\circ}C$

Parameter ¹	Symbol		Values		Unit	Note / Test Condition	
		Min.	Тур.	yp. Max.			
Supply Voltage	V _{DD}	1.7	1.8	1.9	V	-	
Supply Current	,	3.0	5.0	7.0	mA	G0-G3	
Supply Current	I _{DD}	-	0.1	0.15	mA	G4	
RFFE supply voltage	V _{IO}	1.65	1.8	1.95	V	-	
RFFE input high voltage ²	V _{IH}	0.7 * V _{IO}	-	V _{IO}	V	-	
RFFE input low voltage ²	V _{IL}	0	-	0.3 * V _{IO}	V	-	
RFFE output high voltage ³	V _{OH}	0.8 * V _{IO}	-	V _{IO}	V	-	
RFFE output low voltage ³	V _{OL}	0	-	0.2 * V _{IO}	V	-	
RFFE control input capacitance	C _{Ctrl}	-	-	2	pF	-	
RFFE supply current	I _{VIO}	-	3	-	μA	Idle State	

¹Based on the application described in Chapter 5

²SCLK and SDATA

³SDATA

3 RF Characteristics

Table 4: RF Characteristics in ON Mode at T_A = 25 °C, V_{DD} = 1.8 V, I_{VDD} = 5.0 mA, f = 5.15– 5.925 GHz

Parameter	Symbol		Values		Unit	Note / Test Condition
		Min.	Тур.	Max.		
		18.5	20.5	22.5	dB	GO
		15.5	17.5	19.5	dB	G1
Insertion power gain	1/10 12	7.0	9.0	11.0	dB	G2
<i>f</i> = 5500 MHz	$1/ S_{21} ^2$	-2.3	-0.3	1.7	dB	G3
		-5.0	-3.0	-1.0	dB	G3 in Bias0 mode
		-8.0	-6.5	-5.0	dB	G4
		-	1.7	2.2	dB	GO
Noise figure		-	1.7	2.2	dB	G1
f = 5500 MHz	NF	-	1.6	2.1	dB	G2
		-	9.9	10.9	dB	G3
		-	6.5	8.0	dB	G4

Continued on next page



RF Characteristics

Table 4: RF Characteristics - Continued from previous page

Parameter	Symbol		Values	;	Unit	Note / Test Condition
		Min.	Тур.	Max.		
		4	7	-	dB	GO
		4	7	-	dB	G1
Input Return Loss ¹ f = 5500 MHz	RL _{in}	10	20	-	dB	G2
7 – 5500 MHZ		4	8	-	dB	G3
		6	10	-	dB	G4
		10	18	-	dB	GO
Output Return Loss		10	18	-	dB	G1
f = 5500 MHz	RL _{out}	4	7	-	dB	G2
7 – 5500 MHZ		4	7	-	dB	G3
		7	12	-	dB	G4
		28	33	-	dB	GO
Reverse Isolation	1/ S ₁₂ ²	33	38	-	dB	G1
f = 5500 MHz		24	29	-	dB	G2
7 – 5500 MHZ		33	38	-	dB	G3
		5	6.5	-	dB	G4
Inband input 1dB-compression		-22	-18	-	dBm	GO
point	מו	-21	-17	-	dBm	G1
f = 5500 MHz	IP _{1dB}	-10	-6	-	dBm	G2
7 – 5500 MHZ		-1	+3	-	dBm	G3
		-13	-8	-	dBm	GO
Inband input 3 rd -order intercept		-13	-8	-	dBm	G1
point ²	IIP3	-7	-2	-	dBm	G2
point		+1	+6	-	dBm	G3
		+25	+30	-	dBm	G4
Phase discontinuity between all		-12	-	12	0	Part to part variation after com-
Gain Mode combinations						pensation in Base Band with
<i>f</i> = 5500 MHz						constant value
Stability	k	>1	-	-		<i>f</i> = 20 MHz - 10 GHz
	4		1.5	2		50% last SCLK falling edge to
MIPI to RF time	t _{INT}	-	1.5	2	μs	90 % ON, see Fig. 2
Power Up Settling Time	t _{BC}	-	10	25	μs	After power down mode

¹For broadband matching, can be improved by using narrowband matching ²Input power = -30 dBm for each tone for modes G0-G3 / -15 dBm for mode G4, f_1 = 5500 MHz, f_2 = f_1 + 1 MHz



RF Characteristics

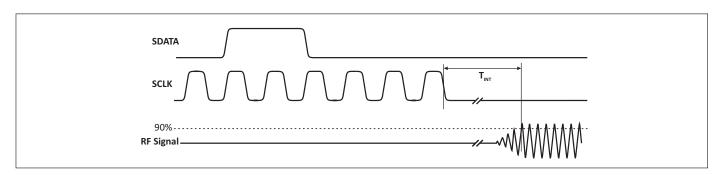


Figure 1: MIPI to RF Time

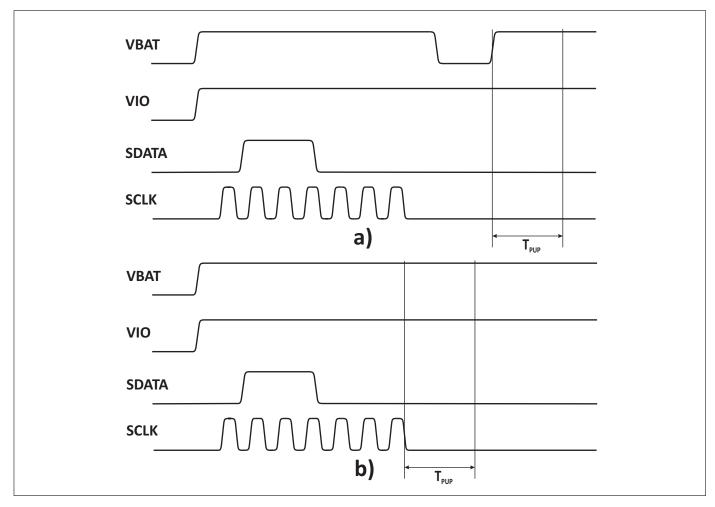


Figure 2: Power-Up Settling Time Definition: a) when the device is already in Active Mode. b) when changing from Low Power Mode to Active Mode.

After Power-Up of VIO the device is set to Low Power Mode. An additional MIPI instruction is necessary to set the device to Active Mode. This case is covered by **b**).



MIPI RFFE Specification

4 MIPI RFFE Specification

All sequences are implemented according to the 'MIPI Alliance Specification for RF Front-End Control Interface' document version 2.0 - 25. September 2014.

Table 5: MIPI Features

Feature	Supported	Comment
MIPI RFFE 2.0 standard	Yes	
Register 0 write command sequence	Yes	
Register read and write command sequence	Yes	
Extended register read and write command se-	Yes	
quence		
Support for standard frequency range operations	Yes	Up to 26 MHz for read and write
for SCLK		
Support for extended frequency range operations	Yes	Up to 52 MHz for write
for SCLK		
Half speed read	Yes	
Full speed read	Yes	
Full speed write	Yes	
Programmable Group SID	Yes	
Programmable USID	Yes	Support for three registers write and extended write se-
		quences
Trigger functionality	Yes	
Broadcast / GSID write to PM TRIG register	Yes	
Reset	Yes	Via VIO, PM TRIG or software register
Status / error sum register	Yes	
Extended product ID register	Yes	
Revision ID register	Yes	
Group SID register	Yes	
USID_Sel pin	Yes	External pin for changing USID:
		USID 12=00 $ ightarrow$ 1000,
		USID 12=10 $ ightarrow$ 1001,
		USID 12=01 $ ightarrow$ 1010,
		USID 12=11 $ ightarrow$ 1011
USID selection via SDATA / SCLK swap feature	No	

Table 6: Startup Behavior

Feature State		Comment
Power status	Low power	Lower power mode after start-up
Trigger function	Enabled	Enabled after start-up. Programmable via behavior control register



MIPI RFFE Specification

Table 7: Register Mapping, Table I

Register Address	Register Name	Data Bits	Function	Description	Default	Broadcast_ID Support	Trigger Support	R/W
0x00	REGISTER_0	7:0	MODE_CTRL	LNA control	00000000	No	Yes	R/W
0x1C	PM_TRIG	7	PWR_MODE(1), Operation Mode	0: Normal operation (ACTIVE)	1	Yes	No	R/W
				1: Low Power Mode (LOW POWER)				
		6	PWR_MODE(0), State Bit Vector	0: No action (ACTIVE)	0]		
				1: Powered Reset (STARTUP to ACTIVE to LOW POWER)				
		5	TRIGGER_MASK_2	0: Data masked (held in shadow REG)	0	No		
				1: Data not masked (ready for transfer to active REG)				
		4	TRIGGER_MASK_1	0: Data masked (held in shadow REG)	0			
				1: Data not masked (ready for transfer to active REG)				
		3	TRIGGER_MASK_0	0: Data masked (held in shadow REG)	0]		
				1: Data not masked (ready for transfer to active REG)				
		2	TRIGGER_2	0: No action (data held in shadow REG)	0	Yes		
				1: Data transferred to active REG]			
		1	TRIGGER_1	0: No action (data held in shadow REG)	0			
				1: Data transferred to active REG				
		0	TRIGGER_0	0: No action (data held in shadow REG)	0			
				1: Data transferred to active REG				
0x1D	PRODUCT_ID	7:0	PRODUCT_ID	This is a read-only register. However, during the programming of the USID a write command sequence is performed on this register, even though the write does not change its value.	00001110	No	No	R
0x1E	MAN_ID	7:0	MANUFACTURER_ID [7:0]	This is a read-only register. However, during the programming of the USID, a write command sequence is performed on this register, even though the write does not change its value.	00011010	No	No	R
0x1F	MAN_USID	7:6	RESERVED	Reserved for future use	00	No	No	R
		5:4	MANUFACTURER_ID [9:8]	These bits are read-only. However, dur- ing the programming of the USID, a write command sequence is performed on this register even though the write does not change its value.	01			
		3:0	USID[3:0]	Programmable USID. Performing a write to this register using the de- scribed programming sequences will program the USID in devices support- ing this feature. These bits store the USID of the device.	See Tab. 5	No	No	R/W



MIPI RFFE Specification

Table 8: Register Mapping, Table II

Register Address	Register Name	Data Bits	Function	Description	Default	Broadcast_ID Support	Trigger Support	R/W
0x20	EXT_PRODUCT_ID	7:0	EXT_PRODUCT_ID		00000000	No	No	R
0x21	REV_ID	7:4	MAIN_REVISION		0001	No	No	R/W
		3:0	SUB_REVISION		0000			
0x22	GSID	7:4	GSID0[3:0]	Primary Group Slave ID.	0000	No	No	R/W
		3:0	RESERVED	Reserved for secondary Group Slave ID.	0000			
0x23	UDR_RST	7	UDR_RST	Reset all configurable non-RFFE Re- served registers to default values. 0: Normal operation 1: Software reset	0	No	No	R/W
		6:0	RESERVED	Reserved for future use	0000000			
0x24	ERR_SUM	7	RESERVED	Reserved for future use	0	No	No	R
		6	COMMAND_FRAME_PARITY_ERR	Command Sequence received with par- ity error — discard command.	0			
		5	COMMAND_LENGTH_ERR	Command length error.	0			
		4	ADDRESS_FRAME_PARITY_ERR	Address frame with parity error.	0			
		3	DATA_FRAME_PARITY_ERR	Data frame with parity error.	0			
		2	READ_UNUSED_REG	Read command to an invalid address.	0			
		1	WRITE_UNUSED_REG	Write command to an invalid address.	0			
		0	BID_GID_ERR	Read command with a BROADCAST_ID or GROUP_ID.	0			
0x78	DFT	7:0	DESIGN_FOR_TEST	Do not use.	-	-	-	-



MIPI RFFE Specification

Table 9: Gain Modes of Operation (Truth Table, Register_0)

REGISTER_0 Bits								
State	Mode	D6	D5	D4	D3	D2	D1	DO
1	Gain G0	1	0	0	1	х	х	x
2	Gain G1	1	0	1	1	х	х	x
3	Gain G2	1	1	0	1	х	х	x
4	Gain G3	1	1	1	0	х	х	x
5	Gain G4 (Bypass)	0	1	1	1	х	х	х

Table 10: Bias settings (Truth Table, Register_0)

		REGISTER_0 Bits							
State	Mode	D6	D5	D4	D3	D2	D1	DO	
9	Bias0 (3.0 mA)	1	x	x	x	0	0	0	
10	Bias1 (3.5 mA)	1	x	x	x	0	0	1	
11	Bias2 (4.0 mA)	1	x	x	x	0	1	0	
12	Bias3 (4.5 mA)	1	x	x	x	0	1	1	
13	Bias4 (5.0 mA) ¹	1	x	x	x	1	0	0	
14	Bias5 (5.5 mA)	1	x	x	x	1	0	1	
15	Bias6 (6.0 mA)	1	x	x	x	1	1	0	
16	Bias7 (6.5 mA)	1	x	x	x	1	1	1	

¹Target bias mode for Gain modes G0-G3



Application Information

BGAU1A10

5 Application Information

Pin Configuration and Function

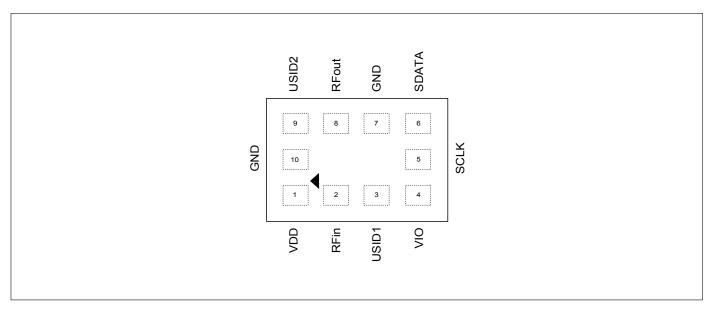


Figure 3: BGAU1A10 Pin Configuration (top view)

Table 11: Pin Definition and Function

Pin No.	Name	Function			
1	VDD	Power supply			
2	RFin	RF input port			
3	USID1	USID select pin 1			
4	VIO	MIPI RFFE supply			
5	SCLK	MIPI RFFE clock			
6	SDATA	MIPI RFFE data			
7	GND	Ground			
8	RFout	RF output port			
9	USID2	USID select pin 2			
10	GND	Ground			

¹ Leave unconnected if not used (do NOT connect to GND)

Low Noise Amplifier with Gain Control



Application Information

Application Board Configuration

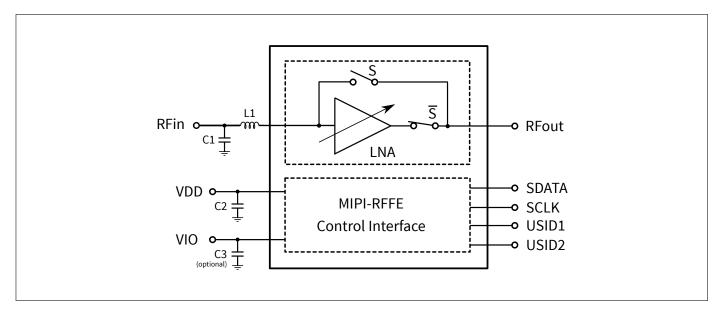


Figure 4: BGAU1A10 Application Schematic

Table 12: Bill of Materials Table

Name	Value	Package	Manufacturer	Function
C1	0.6 pF	0201	muRata GJM type	Input matching ¹
C2	10 nF	0201	Various	RF bypass ²
C3 (optional)	10 nF	0201	Various	RF bypass ²
L1	0.8 nH	0201	muRata LQP type	Input matching ¹
N1	BGAU1A10	ATSLP-10-3	Infineon	Variable gainstep LNA

¹The matching elements must be optimized with reference to the frequency band of interest.

²RF bypass recommended to mitigate power supply noise.

Low Noise Amplifier with Gain Control



Package Information

6 Package Information

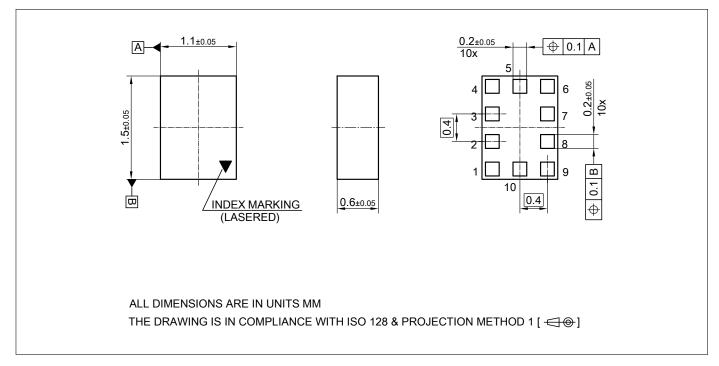


Figure 5: ATSLP-10-3 Package Outline (top, side and bottom views)

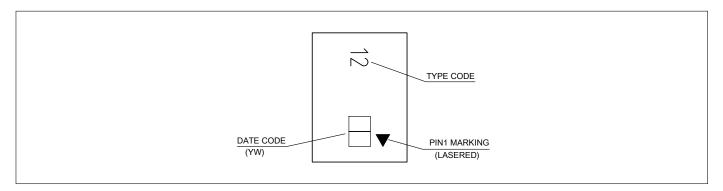


Figure 6: Marking Specification (top view)

Product Name	Marking	Package	
BGAU1A10	U1	ATSLP-10-3	



Package Information

Table 13: Year date code marking - digit "Y"						
Year	"Y"	Year	"Y"	Year	"Y"	
2000	0	2010	0	2020	0	
2001	1	2011	1	2021	1	
2002	2	2012	2	2022	2	
2003	3	2013	3	2023	3	
2004	4	2014	4	2024	4	
2005	5	2015	5	2025	5	
2006	6	2016	6	2026	6	
2007	7	2017	7	2027	7	
2008	8	2018	8	2028	8	
2009	9	2019	9	2029	9	

Table 13: Year date code marking - digit "Y"

Table 14: Week date code marking - digit "W"

Week	"W"	Week	"W"	Week	"W"	Week	"W"	Week	"W"
1	А	12	Ν	23	4	34	h	45	v
2	В	13	Р	24	5	35	j	46	x
3	С	14	Q	25	6	36	k	47	у
4	D	15	R	26	7	37	l	48	z
5	E	16	S	27	а	38	n	49	8
6	F	17	Т	28	b	39	р	50	9
7	G	18	U	29	с	40	q	51	2
8	н	19	V	30	d	41	r	52	3
9	J	20	W	31	e	42	S	53	М
10	к	21	Y	32	f	43	t		
11	L	22	Z	33	g	44	u		



Package Information

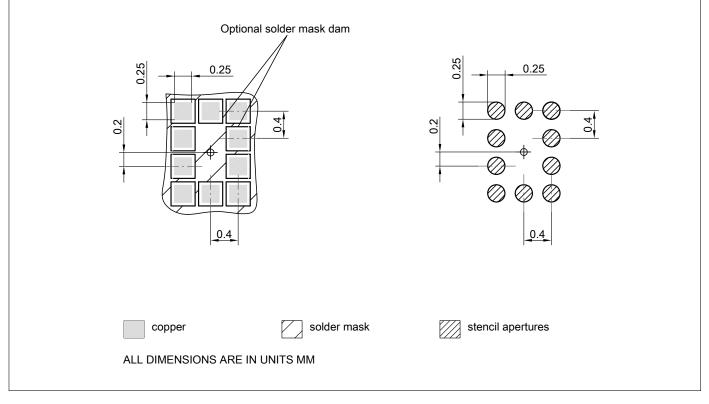


Figure 7: Footprint Recommendation

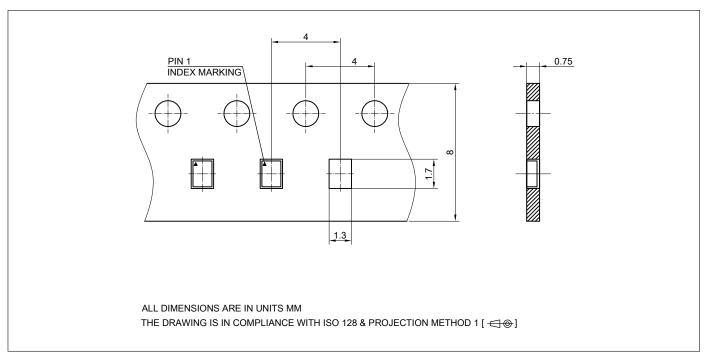


Figure 8: Carrier Tape

Revision History					
Page or Item	Subjects (major changes since previous revision)				
Revision 3.0, 201	Revision 3.0, 2018-04-18				
all	"Preliminary" removed				
2	Maximum current into pin VDD updated				
2	Maximum RF input power updated				
2	Maximum total power dissipation updated				
9	Footnotes updated in Table 11 (Bias settings)				
12	Package outline drawing updated				
12	Marking specification drawing updated				
13	Date code marking tables added				
14	Footprint recommendation drawing added				
14	Carrier tape drawing added				
15	Trademarks updated				

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